# **Single SPST Analog Switch**

The NLAST4501 is an analog switch manufactured in sub–micron silicon–gate CMOS technology. It achieves very low  $R_{ON}$  while maintaining extremely low power dissipation. The device is a bilateral switch suitable for switching either analog or digital signals, which may vary from zero to full supply voltage.

The NLAST4501 is a low voltage, TTL (low threshold) compatible device, pin for pin compatible with the MAX4501.

The Enable pin is compatible with standard TTL level outputs when supply voltage is nominal 5.0 V. It is also over-voltage tolerant, making it a very useful logic level translator.

#### **Features**

- Guaranteed  $R_{ON}$  of 32  $\Omega$  at 5.5 V
- Low Power Dissipation:  $I_{CC} = 2 \mu A$
- Low Threshold Enable pin TTL compatible at 5.0 V
- TTL version and pin for pin with NLAS4501
- Provides Voltage translation for many different voltage levels
   3.3 to 5.0 V, Enable pin may go as high as +5.5 V
   1.8 to 3.3 V
   1.8 to 2.5 V
- Improved version of MAX4501 (at any voltage between 2 and 5.5 V)
- Chip Complexity: FETs = 11
- Pb-Free Packages are Available

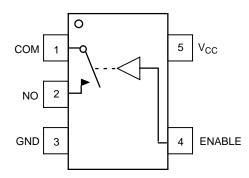


Figure 1. Pinout (Top View)



# ON Semiconductor®

http://onsemi.com



SC70-5/SC-88A/SOT-353 DF SUFFIX CASE 419A



**MARKING** 



TSOP-5 DT SUFFIX CASE 483



A3 = Specific Device Code

M = Date Code\*

A = Assembly Location

Y = Year

W = Work Week

■ = Pb-Free Package

(Note: Microdot may be in either location)
\*Date Code orientation and/or position and underbar
may vary depending upon manufacturing location.

#### **PIN ASSIGNMENT**

| Pin | Function        |
|-----|-----------------|
| 1   | СОМ             |
| 2   | NO              |
| 3   | GND             |
| 4   | ENABLE          |
| 5   | V <sub>CC</sub> |

#### **FUNCTION TABLE**

| On/Off Enable Input | State of Analog Switch |
|---------------------|------------------------|
| L                   | Off                    |
| Н                   | On                     |

#### **ORDERING INFORMATION**

See detailed ordering and shipping information on page 8 of this data sheet.

#### **MAXIMUM RATINGS**

|  | Rating   | Symbol               | Value                        | Unit |
|--|--|----------------------|------------------------------|------|
| Positive DC Supply Voltage                                 |  |                      | -0.5  to  +7.0               | V    |
| Digital Input Voltage (Enable)                             |  | V <sub>IN</sub>      | -0.5  to  +7.0               | V    |
| Analog Output Voltage (V <sub>NO</sub> or V <sub>COM</sub> | )  | V <sub>IS</sub>      | -0.5 to V <sub>CC</sub> +0.5 |      |
| DC Current, Into or Out of Any Pin                         |  | I <sub>IK</sub>      | ±20                          | mA   |
| Storage Temperature Range                                  |  | T <sub>STG</sub>     | -65 to +150                  | °C   |
| Lead Temperature, 1 mm from Case f                         | or 10 Seconds  | TL                   | 260                          | °C   |
| Junction Temperature under Bias                            |  | TJ                   | + 150                        | °C   |
| Thermal Resistance   | SC70-5/SC-88A (Note 1)<br>TSOP-5   | $\theta_{JA}$        | 350<br>230                   | °C/W |
| Power Dissipation in Still Air at 85°C                     | SC70-5/SC-88A<br>TSOP-5  | $P_{D}$              | 150<br>200                   | mW   |
| Moisture Sensitivity                                       |  | MSL                  | Level 1                      |      |
| Flammability Rating  | Oxygen Index: 30% – 35%  | F <sub>R</sub>       | UL 94 V-0 @ 0.125 in         |      |
| ESD Withstand Voltage                                      | Human Body Model (Note 2)<br>Machine Model (Note 3)<br>Charged Device Model (Note 4) | V <sub>ESD</sub>     | > 2000<br>> 100<br>N/A       | V    |
| Latchup Performance  | Above V <sub>CC</sub> and Below GND at 85°C (Note 5)                                 | I <sub>Latchup</sub> | ±300                         | mA   |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- 1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.
- 2. Tested to EIA/JESD22-A114-A.
- 3. Tested to EIA/JESD22-A115-A.
- 4. Tested to JESD22-C101-A.
- Tested to EIA/JESD78.

#### RECOMMENDED OPERATING CONDITIONS

| Parameter   | Symbol  | Min  | Max             | Unit |
|---|---|------|-----------------|------|
| Positive DC Supply Voltage  | V <sub>CC</sub>   | 2.0  | 5.5             | V    |
| Digital Input Voltage (Enable)  | V <sub>IN</sub>   | GND  | 5.5             | V    |
| Static or Dynamic Voltage Across an Off Switch                          | V <sub>IO</sub>   | GND  | V <sub>CC</sub> | V    |
| Analog Input Voltage (NO, COM)  | V <sub>IS</sub>   | GND  | V <sub>CC</sub> | V    |
| Operating Temperature Range, All Package Types                          | T <sub>A</sub>  | - 55 | + 125           | °C   |
| Input Rise or Fall Time, V <sub>cc</sub> (Enable Input) V <sub>cc</sub> | = $3.3 \text{ V} \pm 0.3 \text{ V}$<br>= $5.0 \text{ V} \pm 0.5 \text{ V}$ $t_{r}, t_{f}$ | 0    | 100<br>20       | ns/V |

# DEVICE JUNCTION TEMPERATURE VERSUS TIME TO 0.1% BOND FAILURES

| Junction       |             |             |
|----------------|-------------|-------------|
| Temperature °C | Time, Hours | Time, Years |
| 80             | 1,032,200   | 117.8       |
| 90             | 419,300     | 47.9        |
| 100            | 178,700     | 20.4        |
| 110            | 79,600      | 9.4         |
| 120            | 37,000      | 4.2         |
| 130            | 17,800      | 2.0         |
| 140            | 8,900       | 1.0         |

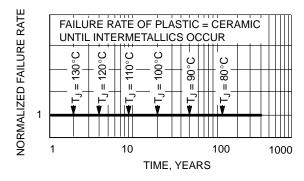


Figure 2. Failure Rate vs. Time Junction Temperature

# DC CHARACTERISTICS - Digital Section (Voltages Referenced to GND)

|   |   |                 |                 | Guaranteed Max Limit |       |        |      |
|---|---|-----------------|-----------------|----------------------|-------|--------|------|
| Parameter                                       | Condition                               | Symbol          | V <sub>CC</sub> | -55°C to 25°C        | <85°C | <125°C | Unit |
| Minimum High-Level Input                        |   | V <sub>IH</sub> | 3.0             | 1.4                  | 1.4   | 1.4    | V    |
| Voltage, Enable Inputs                          |   |                 | 4.5             | 2.0                  | 2.0   | 2.0    |      |
|   |   |                 | 5.5             | 2.0                  | 2.0   | 2.0    |      |
| Maximum Low-Level Input                         |   | V <sub>IL</sub> | 3.0             | 0.53                 | 0.53  | 0.53   | V    |
| Voltage, Enable Inputs                          |   |                 | 4.5             | 0.8                  | 0.8   | 0.8    |      |
|   |   |                 | 5.5             | 0.8                  | 0.8   | 0.8    |      |
| Maximum Input Leakage<br>Current, Enable Inputs | V <sub>IN</sub> = 5.5 V or GND          | I <sub>IN</sub> | 0 V to 5.5 V    | ±0.1                 | ±1.0  | ±1.0   | μΑ   |
| Maximum Quiescent Supply Current (per package)  | Enable and VIS = V <sub>CC</sub> or GND | I <sub>CC</sub> | 5.5             | 1.0                  | 1.0   | 2.0    | μΑ   |

# DC ELECTRICAL CHARACTERISTICS - Analog Section

|   |  |                       |                   | Guarantee      | ed Max Li      | mit            |      |
|---|--|-----------------------|-------------------|----------------|----------------|----------------|------|
| Parameter                                 | Condition  | Symbol                | V <sub>CC</sub>   | -55°C to 25°C  | <85°C          | <125°C         | Unit |
| Maximum ON Resistance<br>(Figures 8 – 12) | $\begin{aligned} V_{IN} &= V_{IH} \\ V_{IS} &= V_{CC} \text{ to GND} \\ I_{IS}I &= \leq 10.0\text{mA} \end{aligned}$             | R <sub>ON</sub>       | 3.0<br>4.5<br>5.5 | 45<br>30<br>25 | 50<br>35<br>30 | 55<br>40<br>35 | Ω    |
| ON Resistance Flatness                    | $V_{IN} = V_{IH}$<br>$I_{IS}I = \le 10.0 \text{ mA}$<br>$V_{IS} = 1 \text{ V}, 2 \text{ V}, 3.5 \text{ V}$                       | R <sub>FLAT(ON)</sub> | 4.5               | 4              | 4              | 5              | Ω    |
| Off Leakage Current, Pin 2 (Figure 3)     | $V_{IN} = V_{IL}$<br>$V_{NO} = 1.0 \text{ V}, V_{COM} = 4.5 \text{ V or}$<br>$V_{COM} = 1.0 \text{ V and } V_{NO} 4.5 \text{ V}$ | I <sub>NO(OFF)</sub>  | 5.5               | 1              | 10             | 100            | nA   |
| Off Leakage Current, Pin 1 (Figure 3)     | V <sub>IN</sub> = V <sub>IL</sub><br>V <sub>NO</sub> = 4.5 V or 1.0 V<br>V <sub>COM</sub> = 1.0 V or 4.5 V                       | I <sub>COM(OFF)</sub> | 5.5               | 1              | 10             | 100            | nA   |

|  |  |  | Guaranteed Max Limit     |                     |                           |                      |        |        |                      |     |       |                      |      |
|--|--|--|--------------------------|---------------------|---------------------------|----------------------|--------|--------|----------------------|-----|-------|----------------------|------|
|  |  |  | v <sub>cc</sub>          | -55                 | °C to                     | 25°C                 |        | < 85°( | С                    |     | <125° | С                    |      |
| Parameter  | Test Conditions  | Symbol   | (V)                      | Min                 | Тур                       | Max                  | Min    | Тур    | Max                  | Min | Тур   | Max                  | Unit |
| Turn-On Time   | $R_L = 300 \Omega$ , $C_L = 35 pF$<br>(Figures 4, 5, and 13) | t <sub>ON</sub>  | 2.0<br>3.0<br>4.5<br>5.5 |                     | 7.0<br>5.0<br>4.5<br>4.5  | 14<br>10<br>9<br>9   |        |        | 16<br>12<br>11<br>11 |     |       | 16<br>12<br>11<br>11 | ns   |
| Turn-Off Time  | $R_L = 300 \Omega$ , $C_L = 35 pF$<br>(Figures 4, 5, and 13) | toff   | 2.0<br>3.0<br>4.5<br>5.5 |                     | 11.0<br>7.0<br>5.0<br>5.0 | 22<br>14<br>10<br>10 |        |        | 24<br>16<br>12<br>12 |     |       | 24<br>16<br>12<br>12 | ns   |
|  |  |  | •                        |                     | •                         | Туріса               | l @ 25 | , vcc  | C = 5.0              | V   |       |                      |      |
| Maximum Input Cap<br>Analog I/O (switch o<br>Common I/O (switch<br>Feedthrough (switch | off)   | C <sub>IN</sub><br>C <sub>NO or</sub> C <sub>NC</sub><br>C <sub>COM(OFF)</sub><br>C <sub>COM(ON)</sub> |                          | 8<br>10<br>10<br>20 |                           |                      |        |        |                      | pF  |       |                      |      |

# ADDITIONAL APPLICATION CHARACTERISTICS (Voltages Referenced to GND Unless Noted)

|   |  |                  | V <sub>CC</sub>   | Limit             |      |
|---|--|------------------|-------------------|-------------------|------|
| Parameter   | Condition  | Symbol           | V                 | 25°C              | Unit |
| Maximum On–Channel –3dB Bandwidth or Minimum Frequency Response | $V_{IS}$ = 0 dBm $V_{IS}$ centered between $V_{CC}$ and GND (Figures 6 and 14)   | BW               | 3.0<br>4.5<br>5.5 | 190<br>200<br>220 | MHz  |
| Maximum Feedthrough On Loss                                     | V <sub>IS</sub> = 0 dBm @ 10 kHz<br>V <sub>IS</sub> centered between V <sub>CC</sub> and GND<br>(Figure 6)   | V <sub>ONL</sub> | 3.0<br>4.5<br>5.5 | -2<br>-2<br>-2    | dB   |
| Off-Channel Isolation   | f = 100 kHz; $V_{IS}$ = 1 V RMS<br>$V_{IS}$ centered between $V_{CC}$ and GND<br>(Figures 6 and 15)  | V <sub>ISO</sub> | 3.0<br>4.5<br>5.5 | -93               | dB   |
| Charge Injection Enable Input to Common I/O                     | $\begin{array}{l} V_{IS} = V_{CC} \text{ to GND, } F_{IS} = 20 \text{ kHz} \\ t_r = t_f = 3 \text{ ns} \\ R_{IS} = 0 \ \Omega, \ C_L = 1000 \text{ pF} \\ Q = C_L * \Delta V_{OUT} \\ \text{(Figures 7 and 16)} \end{array}$ | Q                | 3.0<br>5.5        | 1.5<br>3.0        | pC   |
| Total Harmonic Distortion<br>THD + Noise                        | $F_{IS} = 20 \text{ Hz to 1 MHz}, \ R_L = Rgen = 600 \ \Omega, \ C_L = 50 \ pF$ $V_{IS} = 3.0 \ V_{PP} \ sine \ wave$ $V_{IS} = 5.0 \ V_{PP} \ sine \ wave$ (Figure 17)  | THD              | 3.3<br>5.5        | 0.3<br>0.15       | %    |

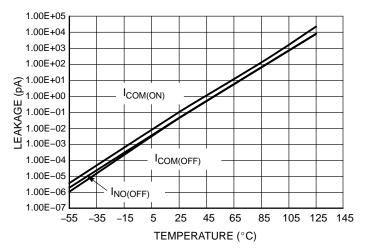


Figure 3. Switch Leakage vs. Temperature

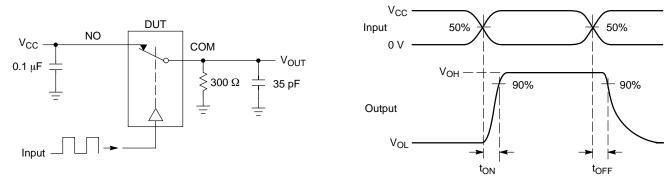


Figure 4. t<sub>ON</sub>/t<sub>OFF</sub>

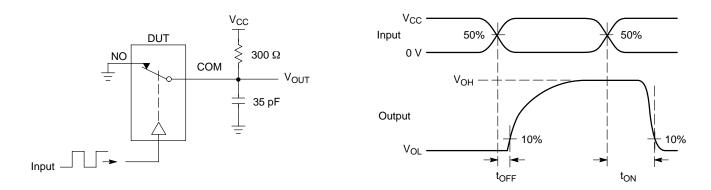
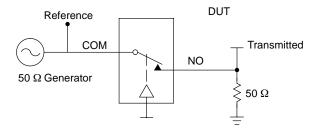


Figure 5. t<sub>ON</sub>/t<sub>OFF</sub>



Channel switch control/s test socket is normalized. Off isolation is measured across an off channel. On loss is the bandwidth of an On switch.  $V_{\text{ISO}}$ , Bandwidth and  $V_{\text{ONL}}$  are independent of the input signal direction.

$$\begin{split} &V_{ISO} = \text{Off Channel Isolation} = 20 \text{ Log } \left(\frac{\text{VOUT}}{\text{VIN}}\right) \text{ for V}_{IN} \text{ at } 100 \text{ kHz} \\ &V_{ONL} = \text{On Channel Loss} = 20 \text{ Log } \left(\frac{\text{VOUT}}{\text{VIN}}\right) \text{ for V}_{IN} \text{ at } 100 \text{ kHz to } 50 \text{ MHz} \end{split}$$

Bandwidth (BW) = the frequency 3 dB below  $V_{ONL}$ 

Figure 6. Off Channel Isolation/On Channel Loss (BW)/Crosstalk (On Channel to Off Channel)/V<sub>ONL</sub>

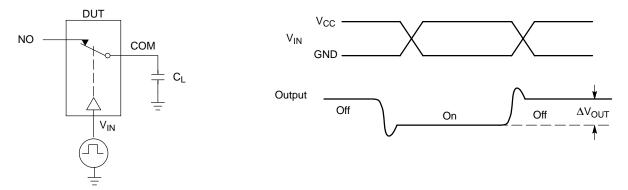


Figure 7. Charge Injection: (Q)

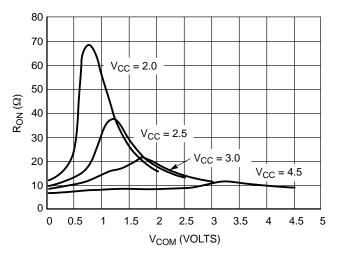


Figure 8. R<sub>ON</sub> vs. V<sub>COM</sub> and V<sub>CC</sub> (@25°C)

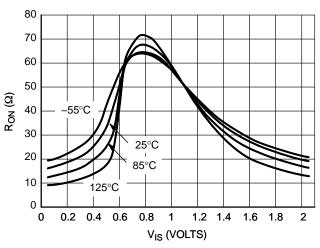


Figure 9.  $R_{ON}$  vs.  $V_{COM}$  and Temperature,  $V_{CC}$  = 2.0 V

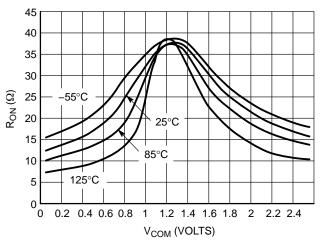


Figure 10. R<sub>ON</sub> vs. V<sub>COM</sub> and Temperature, V<sub>CC</sub> = 2.5 V

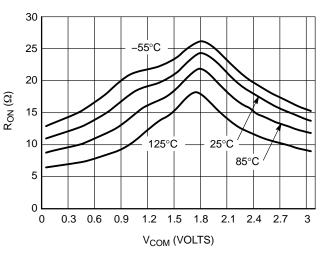


Figure 11. R<sub>ON</sub> vs. V<sub>COM</sub> and Temperature,  $V_{CC}$  = 3.0 V

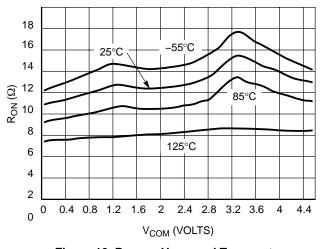


Figure 12.  $R_{\mbox{\scriptsize ON}}$  vs.  $V_{\mbox{\scriptsize COM}}$  and Temperature,  $V_{\mbox{\scriptsize CC}}$  = 4.5 V

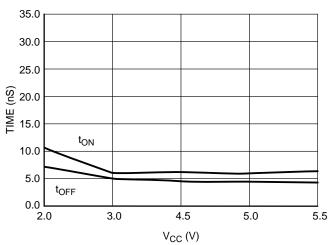


Figure 13. Switching Time vs. Supply Voltage, T = 25°C

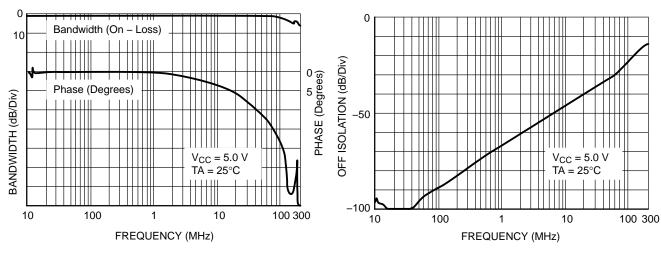


Figure 14. ON Channel Bandwidth and Phase Shift Over Frequency

Figure 15. Off Channel Isolation

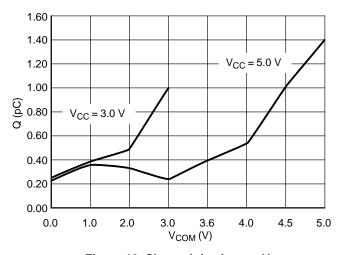


Figure 16. Charge Injection vs.  $V_{COM}$ 

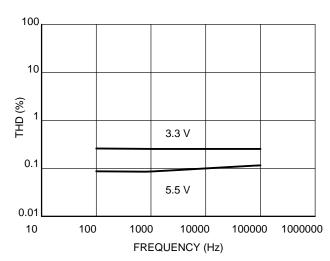


Figure 17. THD vs. Frequency

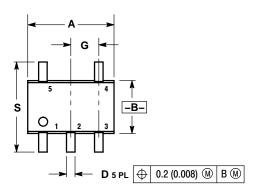
#### **ORDERING INFORMATION**

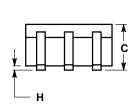
|                |                      | Device     | Nomenclatu         | re                |                          |                                      |                       |
|----------------|----------------------|------------|--------------------|-------------------|--------------------------|--------------------------------------|-----------------------|
| Device         | Circuit<br>Indicator | Technology | Device<br>Function | Package<br>Suffix | Tape &<br>Reel<br>Suffix | Package                              | Shipping <sup>†</sup> |
| NLAST4501DFT2  |                      |            |                    | 5-                | TO                       | SC-88A/SOT-353/<br>SC70              |                       |
| NLAST4501DFT2G | NL                   | AST        | 4501               | DF                | T2                       | SC-88A/SOT-353/<br>SC70<br>(Pb-Free) | 3000/Tape & Reel      |
| NLAST4501DTT1  |                      |            |                    |                   |                          | TSOP-5                               |                       |
| NLAST4501DTT1G |                      |            |                    | DT                | T1                       | TSOP-5<br>(Pb-Free)                  |                       |

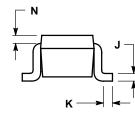
<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

# **PACKAGE DIMENSIONS**

# SC-88A / SOT-353 / SC-70 CASE 419A-02 ISSUE J



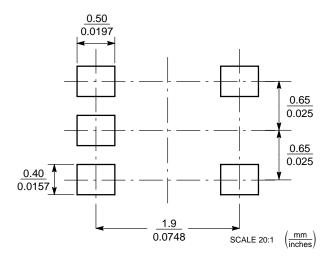




- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. 419A-01 OBSOLETE. NEW STANDARD 419A-02.
  4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

|     | INC              | HES   | MILLIN | IETERS |
|-----|------------------|-------|--------|--------|
| DIM | MIN              | MAX   | MIN    | MAX    |
| Α   | 0.071            | 0.087 | 1.80   | 2.20   |
| В   | 0.045            | 0.053 | 1.15   | 1.35   |
| C   | 0.031            | 0.043 | 0.80   | 1.10   |
| D   | 0.004            | 0.012 | 0.10   | 0.30   |
| G   | 0.026            | BSC   | 0.65   | BSC    |
| Н   |                  | 0.004 |        | 0.10   |
| J   | 0.004            | 0.010 | 0.10   | 0.25   |
| K   | 0.004 0.012 0.10 |       | 0.10   | 0.30   |
| N   | 0.008            | REF   | 0.20   | REF    |
| S   | 0.079            | 0.087 | 2.00   | 2.20   |

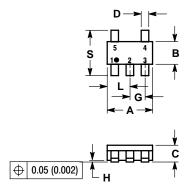
### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### PACKAGE DIMENSIONS

TSOP-5 CASE 483-02 ISSUE E

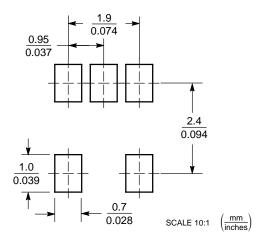




- NOTES:
  1. DIMENSIONING AND TOLERANCING PER
  - ANSI Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETER.
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS
- OF BASE MATERIAL. A AND B DIMENSIONS DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

|     | MILLIN | IETERS | INC    | HES    |
|-----|--------|--------|--------|--------|
| DIM | MIN    | MAX    | MIN    | MAX    |
| Α   | 2.90   | 3.10   | 0.1142 | 0.1220 |
| В   | 1.30   | 1.70   | 0.0512 | 0.0669 |
| С   | 0.90   | 1.10   | 0.0354 | 0.0433 |
| D   | 0.25   | 0.50   | 0.0098 | 0.0197 |
| G   | 0.85   | 1.05   | 0.0335 | 0.0413 |
| Н   | 0.013  | 0.100  | 0.0005 | 0.0040 |
| J   | 0.10   | 0.26   | 0.0040 | 0.0102 |
| K   | 0.20   | 0.60   | 0.0079 | 0.0236 |
| L   | 1.25   | 1.55   | 0.0493 | 0.0610 |
| М   | 0 °    | 10°    | 0°     | 10°    |
| S   | 2.50   | 3.00   | 0.0985 | 0.1181 |

#### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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